

UM11862

BTS6403U Evaluation Board Quick Start Guide

Rev. 1.3 — 15 April 2024

User manual



1 Introduction

This document describes the use, design, and test results of the BTS6403U.

1.1 BTS6403U product description

The BTS6403U is a wideband, high linearity, pre-driver amplifier for 5G massive MIMO infrastructure applications, with fast on-off switching to support TDD systems. The amplifier is designed to operate from 2.3 GHz to 4.2 GHz.

The BTS6403U is housed in a 3 mm x 3 mm x 0.85 mm 16-terminal HVQFN package.

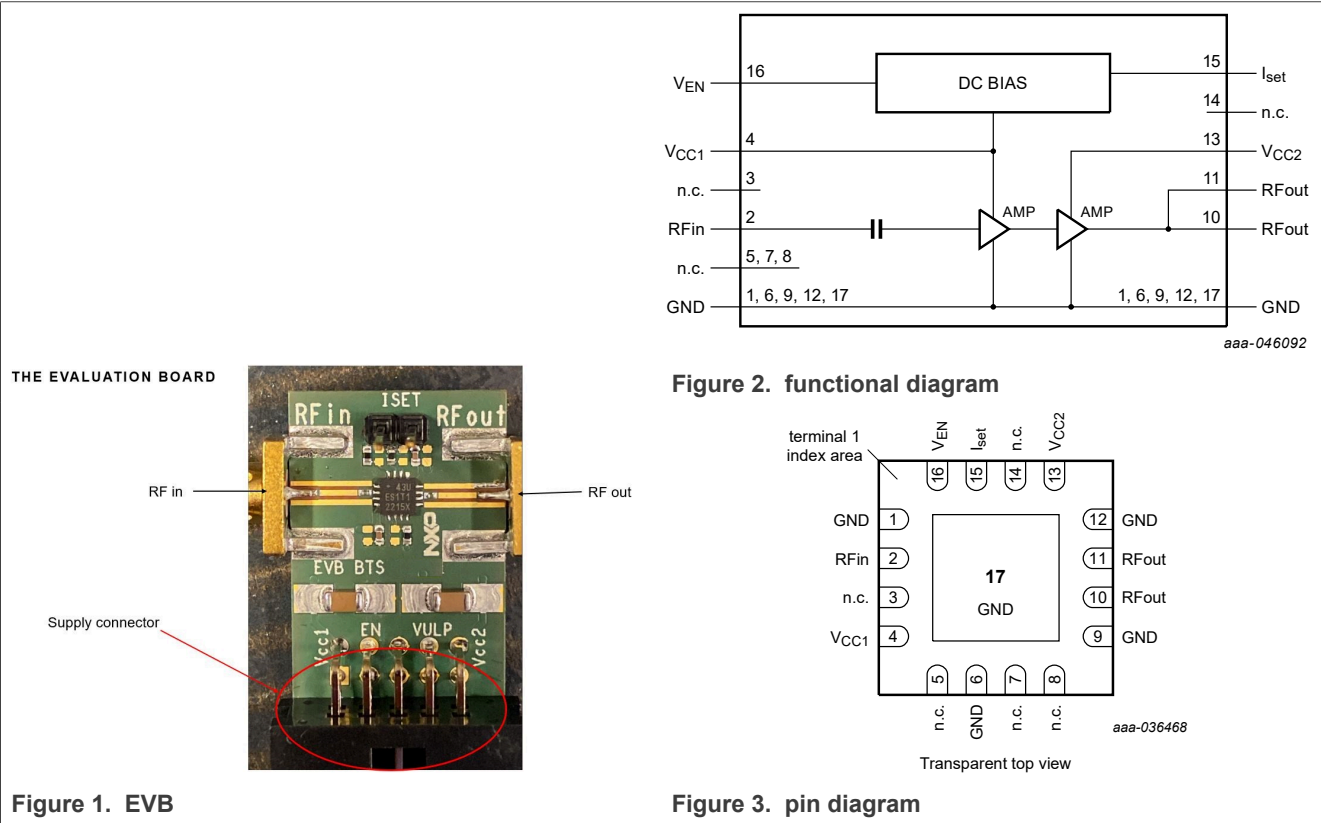
The amplifier is ESD protected on all terminals.

BTS6403U key features and benefits

- High saturated output power $P_{o(sat)} = 29.5$ dBm
- High power-gain $G_p = 38.5$ dB
- High linearity performance ACLR = -45 dBc
- Unconditionally stable
- Fast switching to support TDD systems
- 5 V single supply, quiescent current 100 mA
- Small 16-terminal leadless package 3 mm x 3 mm x 0.85 mm
- ESD protection on all terminals
- Moisture sensitivity level 1

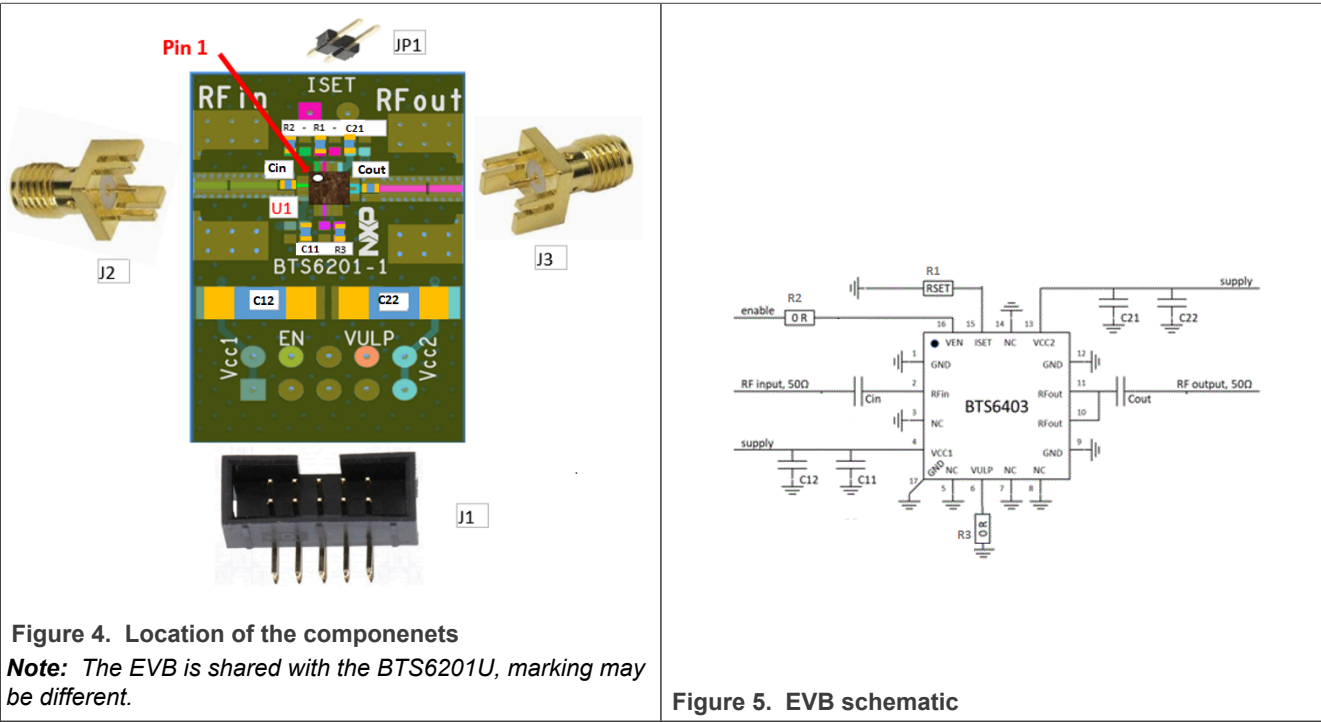


1.1 BTS6403U product description...continued



2 BTS6403U EVB properties

2.1 Schematic



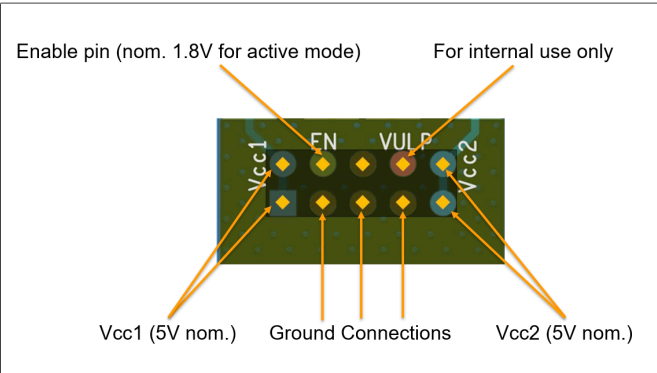
| Resistors, Coils, Capacitors | | | | | | |
|------------------------------|-------|-------------|-----------------------|--------------|--|---------------|
| ID | Shape | Value | Type | Manufacturer | Manufacturer Partnumber | Supplier/type |
| Cin | C0201 | 18 pF Tol: | COG | 25V | GRM0335C1E180JD01D | MURATA |
| Cout | C0201 | 3.9 pF Tol: | COG | 25V | GRM0335C1E3R9BD01D | MURATA |
| C21 | C0402 | 10 nF Tol: | X7R | 25V | GCM155R71E103KA37D | RNELL |
| C11 | C0402 | 10 nF Tol: | X7R | 25V | GCM155R71E103KA37D | FARNELL |
| C12 | C1206 | 10 uF Tol: | X7R | 10V | GRM31CR71A106KA01L | MURATA |
| C22 | C1206 | 10 uF Tol: | X7R | 10V | GRM31CR71A106KA01L | MURATA |
| R1 | R0402 | 10 K Tol: | 0 | 50V | WCR0402-10KFA | YAGEO |
| R2 | R0402 | 0 R Tol: | 0 | 0 | RC0402JR-070RL | FARNELL |
| R3 | R0402 | 0 R Tol: | 0 | 0 | RC0402JR-070RL | FARNELL |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| | - | - | - | - | | - |
| ID | Value | | Manufacturer | | Manufacturer Partnumber | Supplier/type |
| JP1 | | | 0 | | PIN HEADER Vertical - single row 3 2,5mm pitch | Texim-Europe |
| J2 | | | JOHNSON EMERSON | | CONNECTOR SMA CONN JACK END LAUNCH PC GOLD SMA-1,2mm | DIGI-KEY |
| J3 | | | JOHNSON EMERSON | | CONNECTOR SMA CONN JACK END LAUNCH PC GOLD SMA-1,2mm | DIGI-KEY |
| J1 | | | Amphenol Socapex T821 | | PIN HEADER 10 Way, 2 Row, Right Angle, through hole | RS-online |
| EVB | | | 0 | | PCB BTS6201X Tiger Shakti EVB (BTS6303) | Cibel |

Figure 6. Bill of materials

2.2 DC and control connections

Figure 7 shows the DC and enable connection, at the main header (J1). The connector can be straight or 90 degrees. The text is also on the EVB. Figure 8 shows connections JP1 GND, and JP1 ISET. JP1 (ISET) on the EVB can be applied to adjust the quiescent current in the final stage of the amplifier. R1 should be removed in case JP1 is applied to adjust the bias current.

Note: NXP recommends that, using the setup as is shown in Figure 8 is R1 (10 kΩ).



Enable pin (nom. 1.8V for active mode) For internal use only

Vcc1 (5V nom.) Ground Connections Vcc2 (5V nom.)

Figure 7. Main header J1

Note: Connector may be straight or 90 degrees angled.

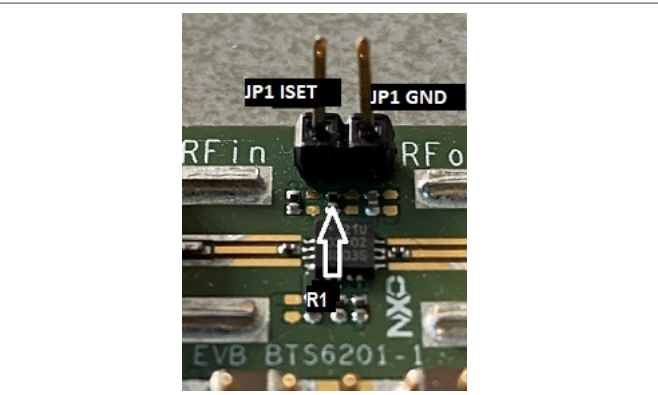
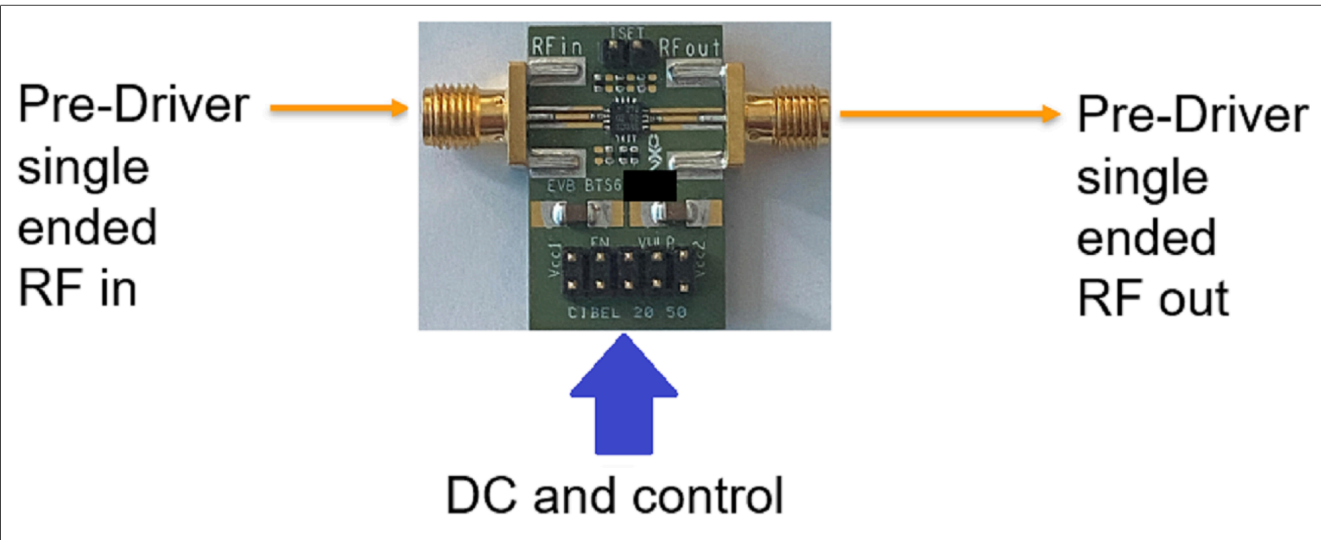


Figure 8. JP1

2.3 Operations

Figure 9 shows the connections in a single ended to single ended operation.

If differential to single ended operation is also needed, NXP refers to UM11918 of the BTS6305U.



Pre-Driver single ended RF in

Pre-Driver single ended RF out

DC and control

Figure 9. Single ended to single ended operation

3 Measurements results

In the below graphics, the Spar measurements are shown. Measured at nominal conditions $V_{CC} = 5\text{ V}$, $T_{case} = 25\text{ }^{\circ}\text{C}$, $R_{set} = 10\text{ K}\Omega$.

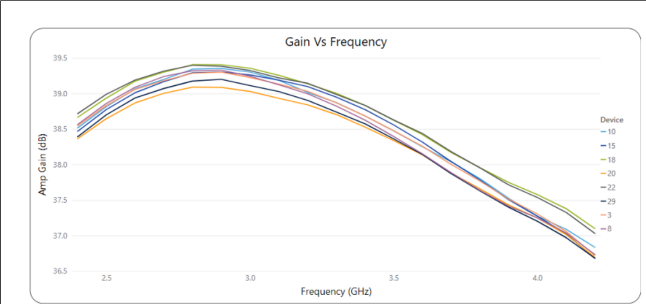


Figure 10. Gain at nominal conditions

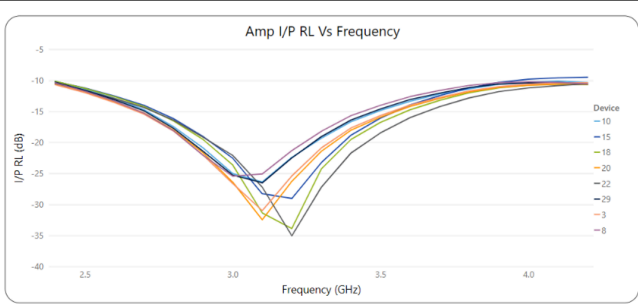


Figure 11. RL_i at nominal conditions

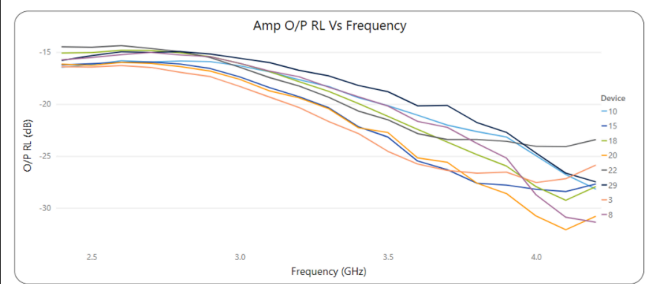


Figure 12. RL_o at nominal conditions

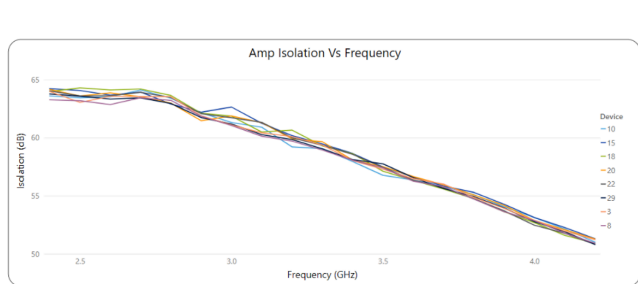


Figure 13. ISL_r (Gain mode) at nominal conditions

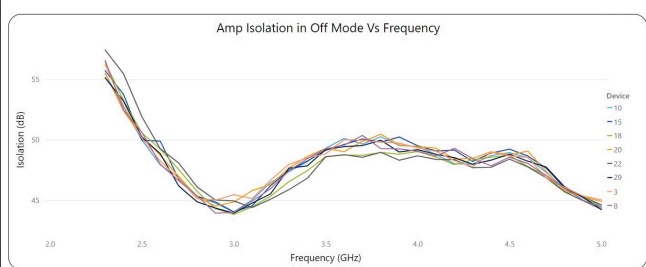


Figure 14. ISL_r (off mode) at nominal conditions

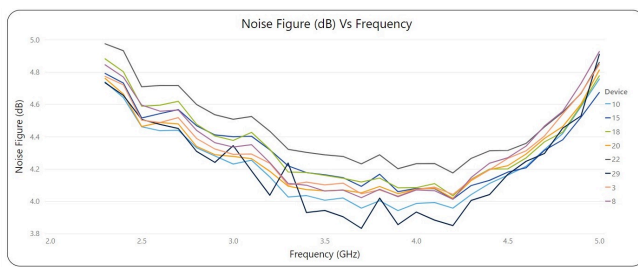


Figure 15. NF at nominal conditions


4 Abbreviations

Table 1. Abbreviations

| Acronym | Description |
|---------|--|
| ACLR | adjacent channel leakage ratio |
| ESD | electrostatic discharge |
| EVB | evaluation board |
| MIMO | massive multiple-input multiple-output |
| RF | radio frequency |
| TDD | time-division duplexing |

5 EMC information

CAUTION



This product has not undergone formal EMC assessment. It is the responsibility of the user to ensure that any finished assembly complies with applicable regulations on EMC interference. EMC testing, and other testing requirements for CE is the responsibility of the user.

6 Revision history

Table 2. Revision history

| Document ID | Release date | Description |
|------------------|------------------|---|
| UM11862 Rev. 1.3 | 15 April 2024 | • Updated Legal information and brought to current standard |
| UM11862 Rev. 1.2 | 23 May 2023 | • Updated |
| UM11862 Rev. 1.1 | 7 December 2022 | • Added EMC information |
| UM11862 Rev. 1 | 18 November 2022 | • Initial release of user manual |

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